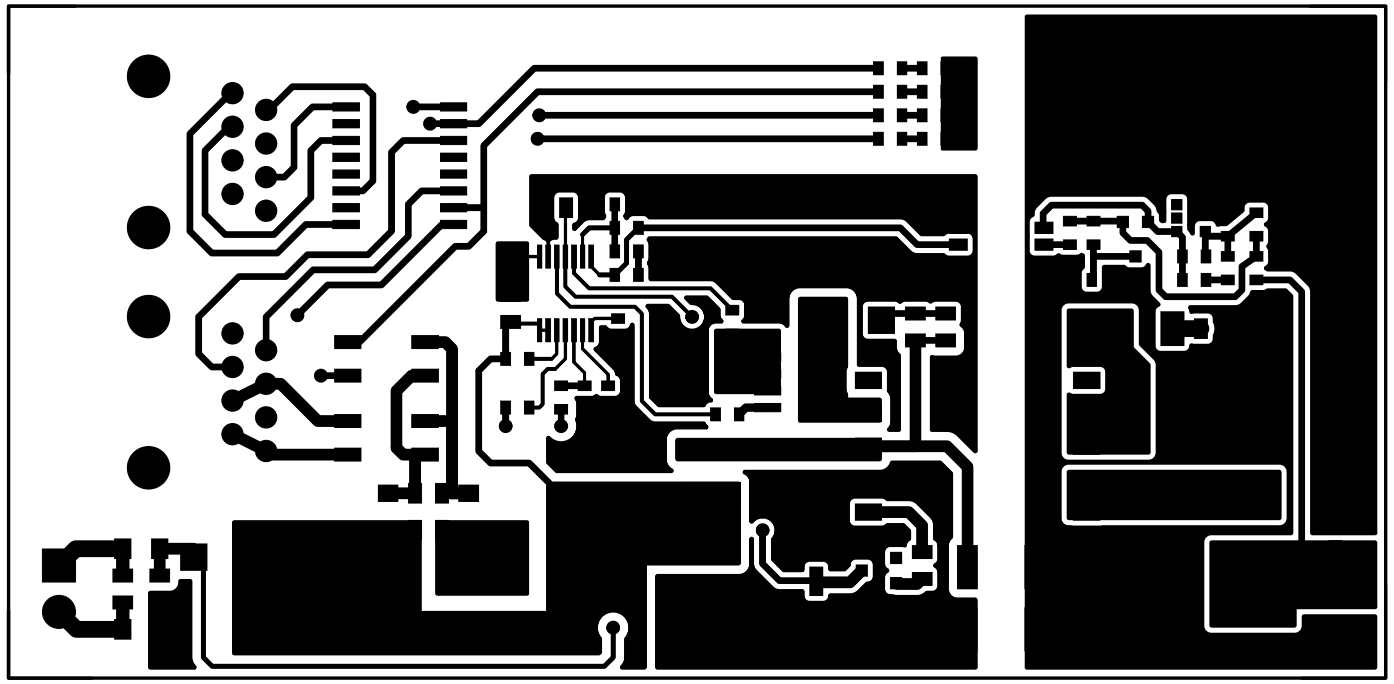
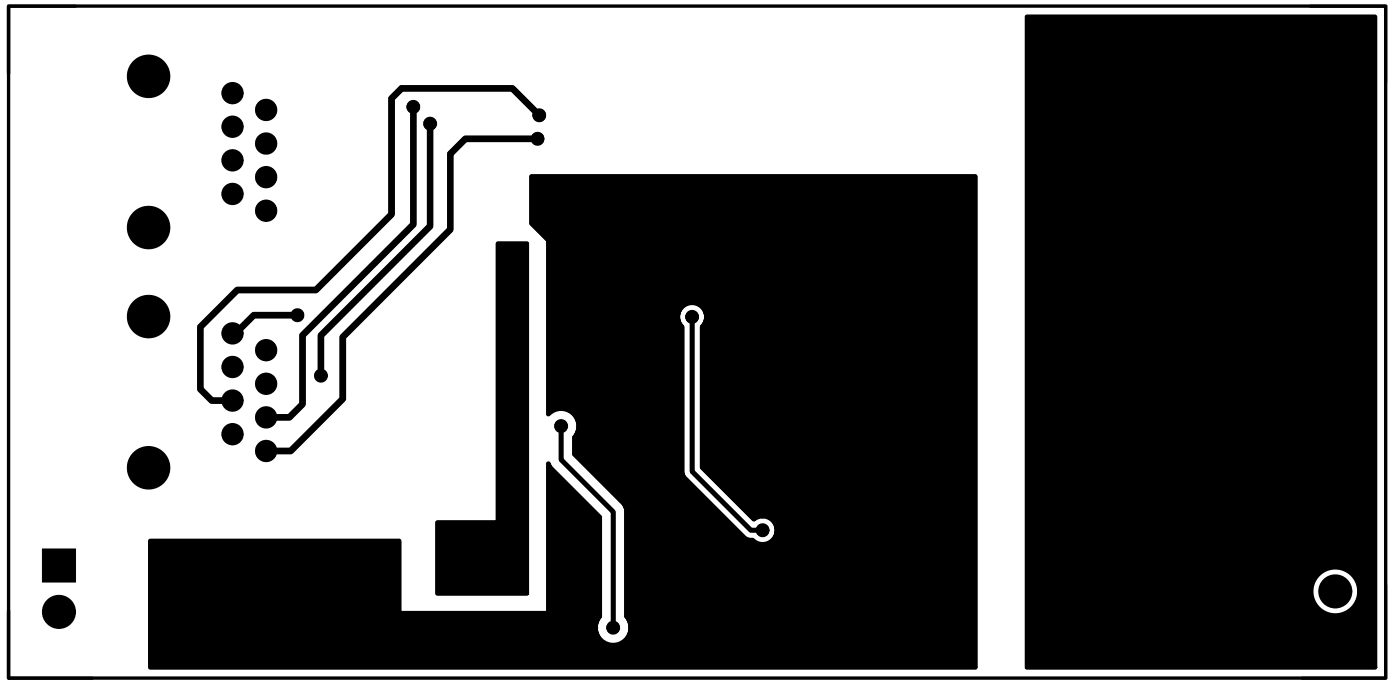


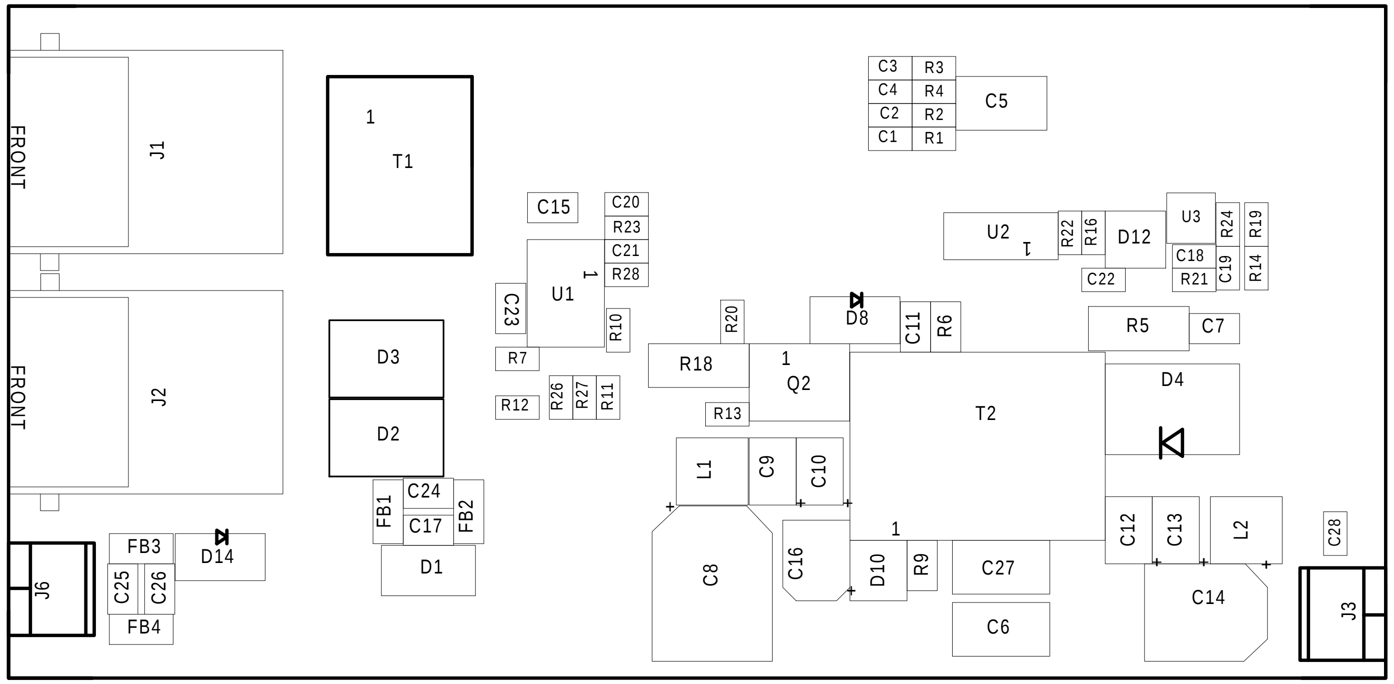
TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. {Project Number}	Rev. B	L1										

Date: {Start Date}	Filename: PMP7355B.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}	Software PADs v9.3



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. {Project Number}	Rev. B		L2									

Date: {Start Date}	Filename: PMP7355B.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}	Software PADs v9.3



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. {Project Number}	Rev. B	L1								TA		
Date: {Start Date}	Filename: PMP7355B.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}	Software PADs v9.3							

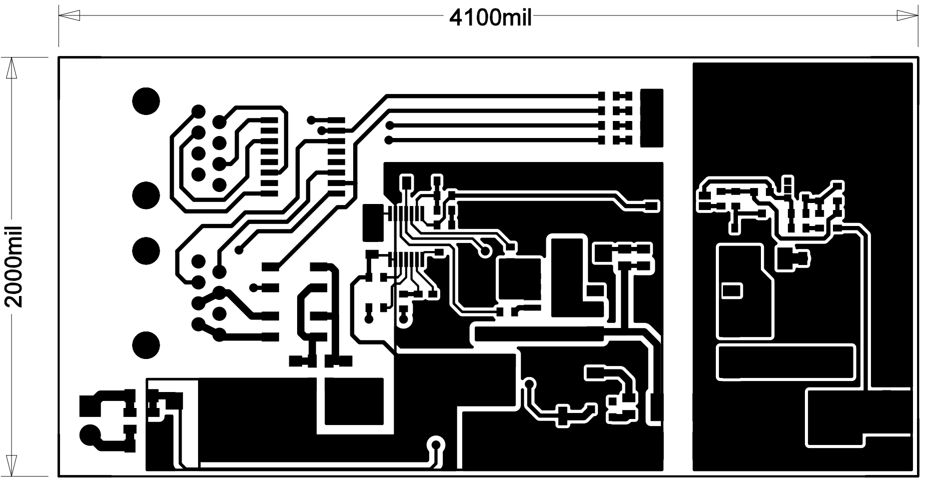
Copper Layer Number		Silkscreen		S Mask		P Mask		Assembly	
Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot
	L2								BA

Fab Drawing

TEXAS INSTRUMENTS

Board No. {Project Number}	Rev. B

Date: {Start Date}	Filename: PMP7355B.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH	Modified Date: {Modification Date}	Software PADs v9.3



FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
☐ 0.031	■ LAYER 1	■ LAYER 1	☐ 1 OZ.
■ 0.062	☐ LAYER 2	■ LAYER 2	■ 2 OZ.
☐ 0.093	☐ NONE	☐ NONE	☐ OTHER ____
☐ 0.125			________

DESIGN	TRACE/GAP SPACING	LAYER COUNT
☐ SMD	■ 0.010/0.010	☐ SINGLE SIDED
☐ THRU-HOLE	☐ 0.008/0.007	■ 2 LAYER
■ MIX	☐ 0.006/0.006	☐ 4 LAYER
		☐ OTHER ________

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES: UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

<table>
<tr><td colspan="2" rowspan="2">TEXAS INSTRUMENTS</td><td colspan="2">Copper Layer Name</td><td colspan="2">Silkscreen</td><td colspan="2">S Mask</td><td colspan="2">P Mask</td><td colspan="2">Assembly</td><td rowspan="2">Fab Drawing</td></tr>
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</table>

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